

# 高速傳輸軟性基板用低粗超度高彎折性電解銅箔

Very Low Profile of high bending property copper foil

## 型號: 3EC-M2S-HTE SP2 & 3EC-M2S-HTE SP3

### 高速傳輸軟性基板用低粗超度高彎折性電解銅箔

Suitable for High Speed High Frequency and Fine pattern FPCBs design with excellent Bending Performance.

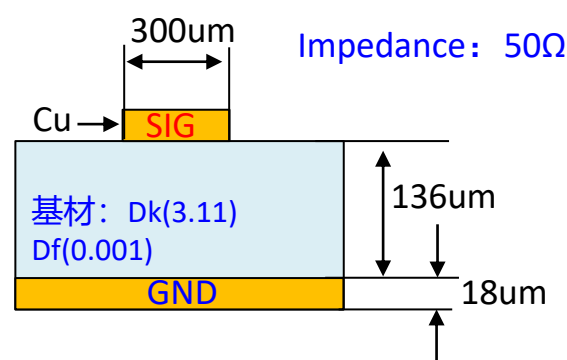
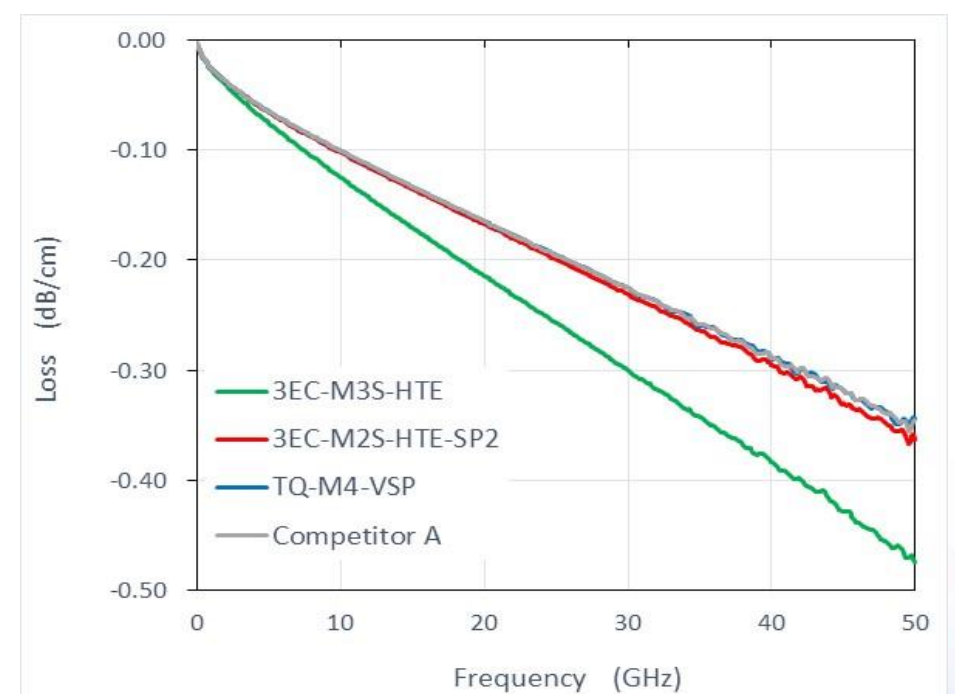
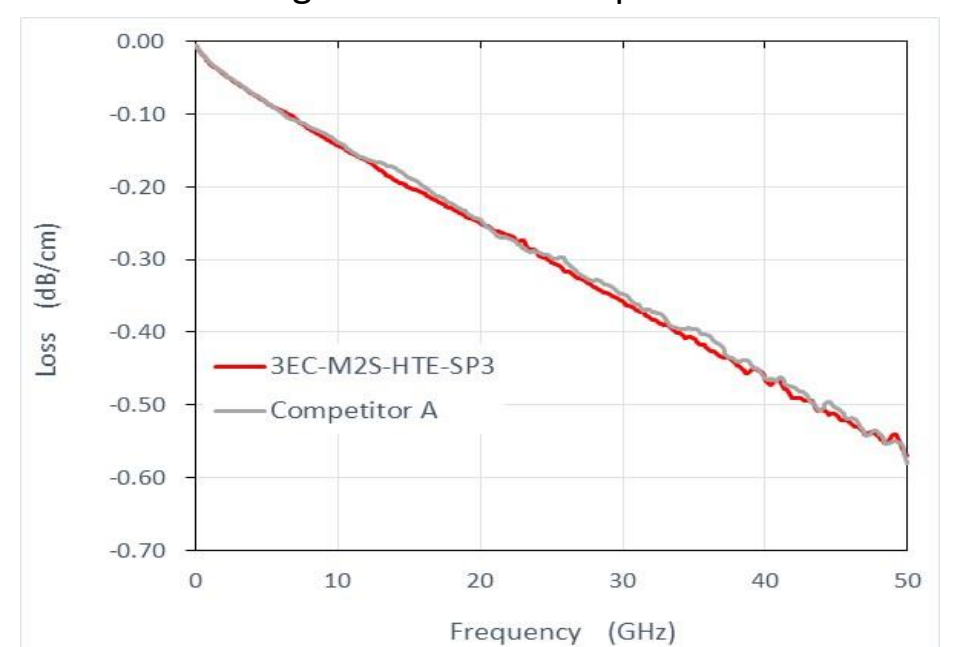
### 適合搭配MPI, 信號傳輸損耗低, 效果好

Excellent Signal Insertion lost performance with Modified PI.

### 剝離强度高

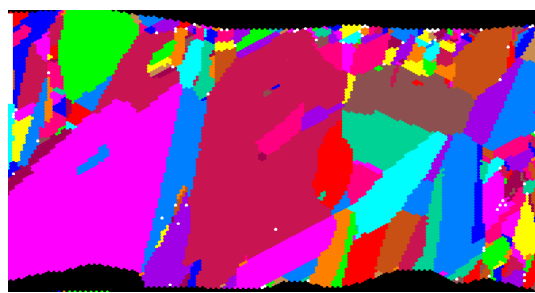
Good Bonding strength.

Signal Insertion loss performance



#### 型號: 3EC-M2S-HTE SP2/SP3

Average crystal size: 6.5μm

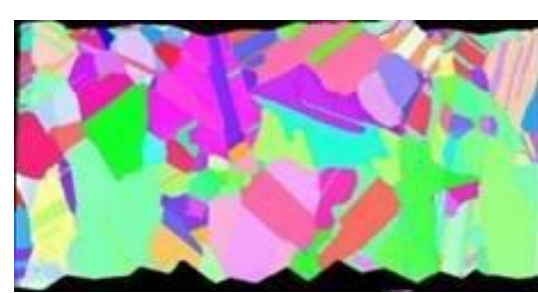


※After 180C, 1hr

3μm

#### Class III

Average crystal size: 2.5μm



※After 180C, 1hr

3μm

	Surface roughness Lam. Side [μm]	Cross Section Image	Thickness [μm]
Normal Profile (Reference)	3EC-M3S-HTE	Rz 2.5	12 μm
Very Low Profile	3EC-M2S-HTE-SP2	Rz ~ 1.4	18 μm
Super Low Profile	3EC-M2S-HTE-SP3	Rz 0.9 ~ 1.1	9μm, 12 μm, 18um, 35um

\* Mass Production in Mitsui Copper Foil Malaysia plant.

Excellent Copper Foil characteristic for Advance Flexible Board application.

### 三井金屬特有的高彎折性銅箔加上低粗超度處理。

- Mitsui proprietary high bending property copper foil with very low profile treatment.

### 應用於高頻高速上表現超低損耗。

- Improved Signal lost performance in High speed High frequency application.

### 產能高, 足以滿足客戶量產需求。

- Good track record of reliable and advance production capability to fulfil customers' volume requirement.



三井金屬